



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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Product Summary

V_{BR} (Min)	I_{PP} (Max)	C_T (Typ)
15V	50A	320pF

Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability makes it ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Applications

- Cellular Handsets
- Portable Electronics
- Computers and Peripheral

Features

- Provides ESD Protection per IEC 61000-4-2 Standard: Air ±30kV, Contact ±30kV
- One Channel of ESD Protection
- Low Channel Input Capacitance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: U-DFN1610-2 (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.003 grams (Approximate)



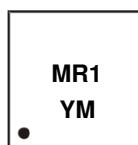
Device Schematic

Ordering Information (Note 4)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
D14V0H1U2LP1610-7	Standard	MR1	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



MR1 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: E = 2017)
 M = Month (ex: 9 = September)

Date Code Key

Year	2015	2016	2017	2018	2019	2020
Code	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I _{PP}	50	A	8/20μs (Note 7)
Peak Pulse Power Dissipation	P _{PP}	1120	W	8/20μs (Note 7)
ESD Protection – Contact Discharge	V _{ESD_CONTACT}	±30	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V _{ESD_AIR}	±30	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	300	mW
Thermal Resistance, Junction to Ambient T _A = +25°C	R _{θJA}	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	—	—	14	V	—
Channel Leakage Current (Note 6)	I _R	—	—	0.3	μA	V _R = 14.0V
Reverse Breakdown Voltage	V _{BR}	15	—	—	V	I _R = 1mA
Clamping Voltage, Positive Transients (Note 7)	V _C	—	—	18	V	I _{PP} = 1A, t _p = 8/20μs
		—	—	19	V	I _{PP} = 10A, t _p = 8/20μs
		—	—	23.5	V	I _{PP} = 50A, t _p = 8/20μs
Channel Input Capacitance (Note 8)	C _T	—	320	—	pF	V _R = 0V, f = 1MHz, Any I/O to GND
Dynamic Resistance	R _{DYN}	—	0.05	—	Ω	TLP, 10A, t _p = 100ns

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - Short duration pulse test used to minimize self-heating effect.
 - Clamping voltage value is based on an 8x20μs peak pulse current (I_{pp}) waveform.
 - Measured from any I/O to GND.
 - For information on the impact of Diodes Incorporated's USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: <https://www.diodes.com/assets/App-Note-Files/AN77.pdf>.

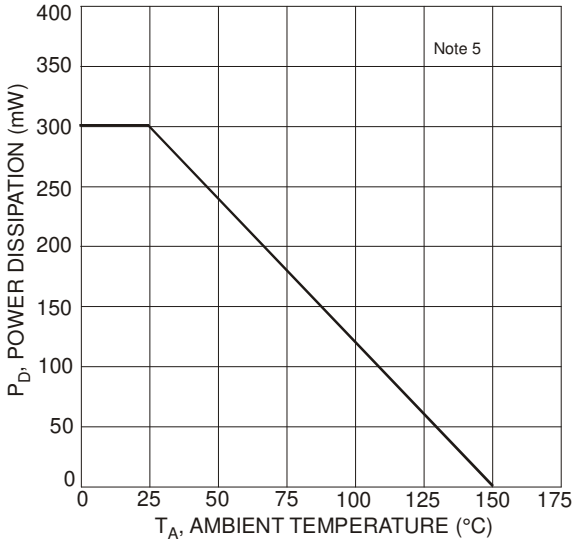


Figure 1 Power Derating Curve

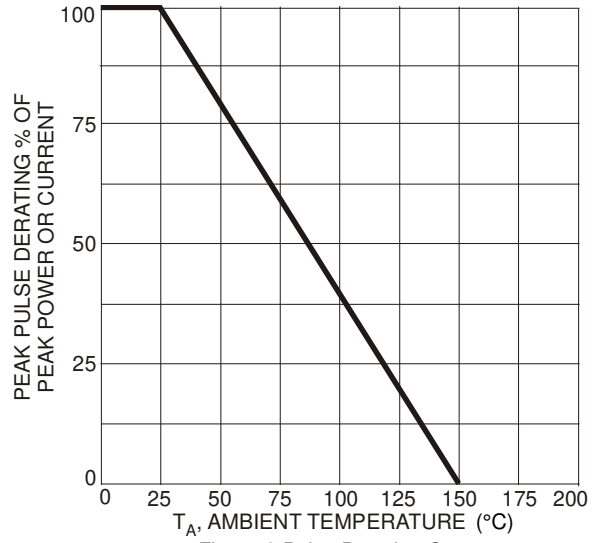


Figure 2 Pulse Derating Curve

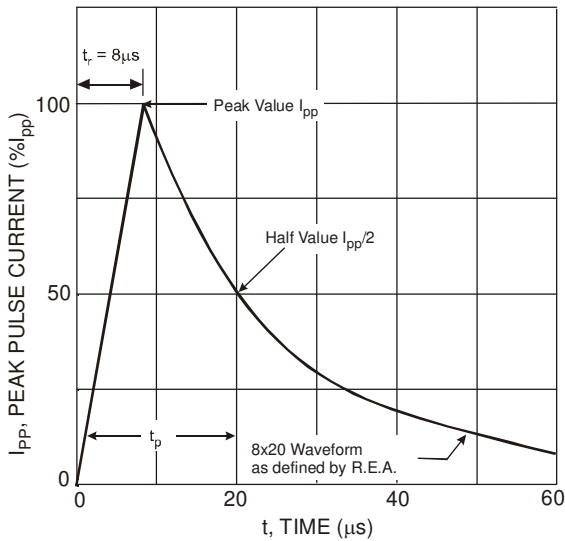


Figure 3 Pulse Waveform

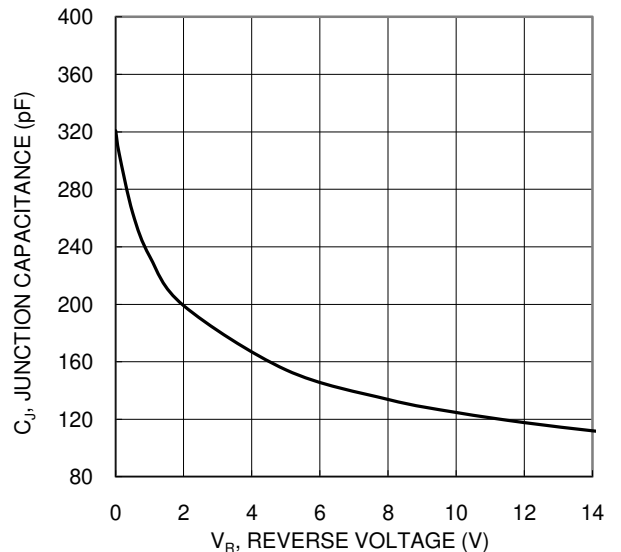
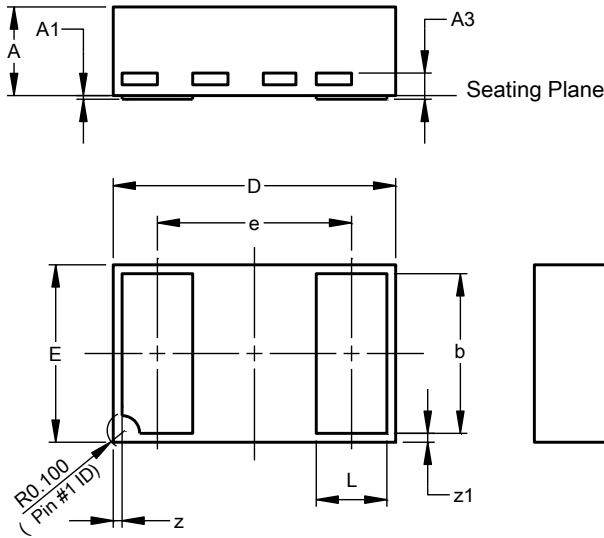


Figure 4 Typical Junction Capacitance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN1610-2 (Type B)

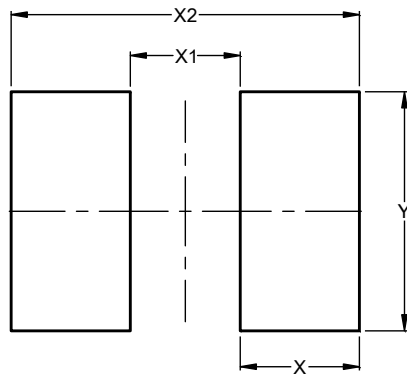


U-DFN1610-2 (Type B)			
Dim	Min	Max	Typ
A	0.45	0.55	0.50
A1	0.00	0.05	0.015
A3	-	-	0.127
b	0.85	0.95	0.90
D	1.55	1.65	1.60
E	0.95	1.05	1.00
e	-	-	1.10
L	0.35	0.45	0.40
z	0.050 REF		
z1	0.050 REF		
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN1610-2 (Type B)



Dimensions	Value (in mm)
X	0.650
X1	0.600
X2	1.900
Y	1.300

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